

Message Text

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PAGE 01 STATE 201104

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TO USMISSION OECD PARIS

C O N F I D E N T I A L STATE 201104

EXCON

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TAGS:ESTC, COCOM, PL, US

SUBJECT: US EPOXY BONDERS TO POLAND IL - 1355

REFS: (A) COCO; DOC.(76)332, (B) OECD PARIS 22705, (C)
STATE 193731, (D) OC DOC.5394 AND (E) OECD PARIS 07858

1) WE APPRECIATE YOUR CALLING TO OUR ATTENTION IN REF B THE PROBLEMS WHICH COULD ARISE FROM THE USE OF THE INFORMATION CONTAINED IN REF C IN ANSWERING THE FRENCH EX POST FACTO QUESTIONS (REF E) RE REF A. WE ALSO APPRECIATE THE SEEMING CONFLICT BETWEEN THE TTG RECOMMENDATION CONTAINED IN REF D AND CITED IN PARA 1 OF REF B AND THE FINAL US PROPOSED TABLED IN COCOM DOC REV (74)1355/8. THAT TTG RECOMMENDATION WAS MADE PRIOR TO ROUND II OF THE 1974-75 LIST REVIEW AND WAS INCLUDED IN REF D, AS AN INDICATION OF THE TECHNICAL THINKING AS OF JULY 1975.

2) AS FOR REF A, THE OPERATIVE FEATURES OF THE FINAL US PROPOSAL IN 1355/8 ARE: (1) COVERAGE IN SUB-ITEM (B)(3)(1)
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PAGE 02 STATE 201104

OVER AUTOMATIC/SEMI-AUTOMATIC BONDERS AND WELDERS AND (2)

DELETION OF SUB-ITEM (C) WHICH WOULD FREE EQUIPMENT FOR THICK FILM DEPOSITION. ALTHOUGH THE PROPOSAL IN 1355/8 WAS NOT ACCEPTED, THE US, NEVERTHELESS, IS TRAMMELLED BY IT AND HERE LIES PART OF THE TECHNICAL DELEMMA RE THE EPOXY

BONDERS IN REF A AND THE PARAMETERS OF THE FORTHCOMING 1355 REDEFINITION THE US UNDERTOOK TO TABLE IN THE DEF SERIES.

3) EPOXY BONDING IS AN ALTERNATIVE TECHNIAUE DEVELOPED FOR ATTACHING SEMICONDUCTOR CHIPS TO SUBSTRATES IN SITUATIONS WHERE THE HEAT USED IN THE EUTECTIC DIE BONDING OR REFLOW SOLDER METHODS WOULD ALTER THE PERFORMANCE OF THE CHIP. THE EPOXY TECHNIQUE IS NOT PERFERRED FOR USE IN MAKING HIGH RELIABILITY OR MILITARY - USE CHIPS BE- CAUSE OF THE TEMPERATURE SHIFTS AFFECTING THE ADHESIVE QUALITY OF THE BONDED CHIP. THE EPOXY TECHNIQUE IS IN THE THICK FILM CATEGORY AND AS SUCH ITS EQUIPMENT WOULD BE FREED UNDER THE 1355/8 PROPOSAL. AUTOMATIC AND SEMI-AUTOMATIC BONDERS, HOWEVER, ARE CAPABLE OF BONDING FOR BOTH THICK AND THIN FILM CIRCUITS AND, THEREFORE, FALL UNDER SUB-ITEM (B)(3)(1) OF 1355/8. THE EPOXY BONDERS IN REF A ARE CAUGHT IN THIS THICK/THIN FILM OVERLAP, EVEN THOUGH MANUALLY OPERATED.

4) AS FOR THE FRENCH QUESTIONS IN REF E RE DIVERSION, WE CAN OFFER NO MORE OF A GUARANTEE THAN CAN ANY OTHER COCOM MEMBER IN A SIMILAR SITUATION. THEREFORE, IN REPLYING TO THE FRENCH QUESTIONS YOU SHOULD DISREGARD REF C AND POINT OUT THAT THE EPOXY TECHNIQUE IS NOT NORMALLY USED TO PRODUCE HIGH QUALITY OR MILITARY-USE CHIPS AND ON THIS BASIS THE US BELIEVES THE MOST LIKELY END-USE OF THE PRODUCTS OF THE BONDERS IN REF A WILL BE IN THE CIVIL AREA.

5) THE TENOR OF THE FRENCH QUESTIONS SUGGESTS THAT THEY ARE NEEDLING US RE THICK FILM DEPOSITION EQUIPMENT SINCE SUCH EQUIPMENT WOULD BE FREE UNDER THE DELETION OF 1355 SUB-ITEM (C) IN THE US REDEFINITION PROPOSED IN 1355/8. EVEN IF THE BONDERS IN REF A WERE CAPABLE OF CONFIDENTIAL

CONFIDENTIAL

PAGE 03 STATE 201104

ONLY BEING USED IN CONJUNCTION WITH THICK FILM CIRCUITS, WE WOULD STILL HAVE TO SUBMIT REF A TO THE COMMITTEE, GIVEN THE UNRESOLVED STATUS OF IL-1355. KISSINGER

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